

/ Absolute Maximum Ratings(Ta=25)

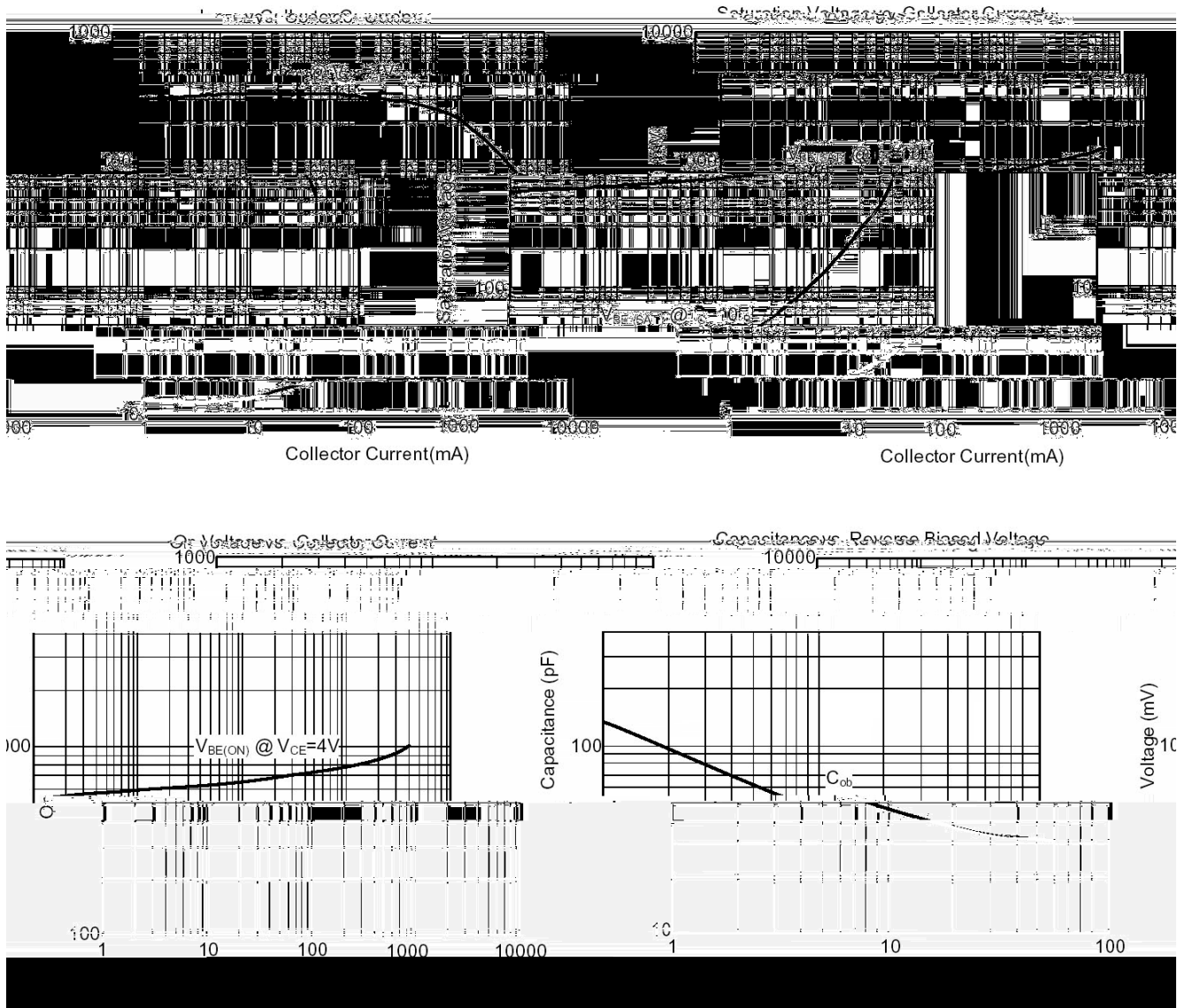
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-70	V
Collector to Emitter Voltage	V_{CEO}	-50	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-4.0	A
Base Current - Continuous	I_{CP}	-8.0	A
Collector Power Dissipation	$P_C(T_C=25^{\circ}C)$	40	W
Junction Temperature	T_j	150	$^{\circ}C$
Storage Temperature Range	T_{stg}	-55 150	$^{\circ}C$

/ Electrical Characteristics(Ta=25)

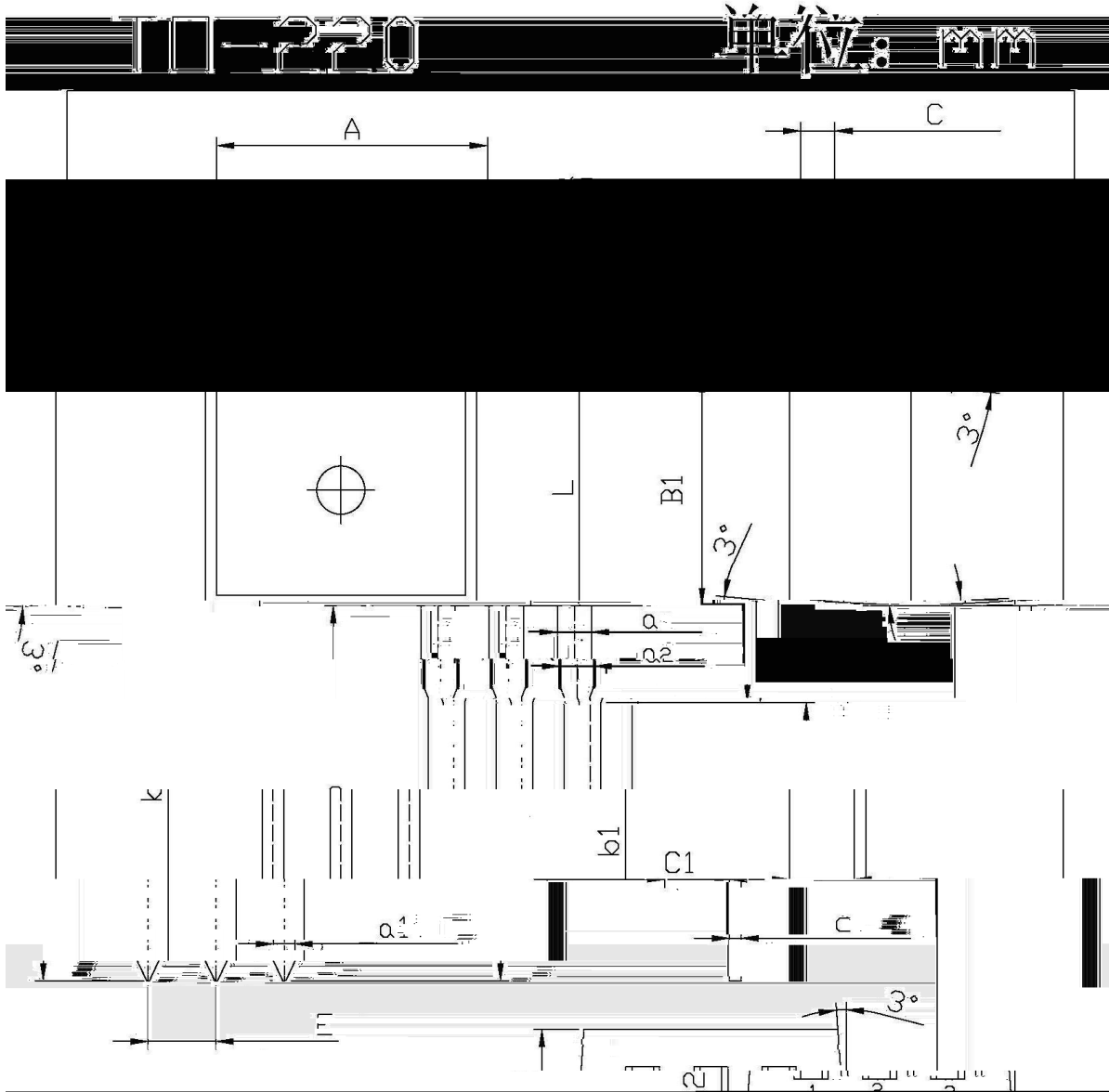
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C=-10\text{ A}$ $I_E=0$	-70			V
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=-50\text{mA}$ $I_B=0$	-50			V
Emitter to Base Breakdown Voltage	V_{EBO}	$I_E=-10\text{ A}$ $I_C=0$	-5.0			V
Collector Cut-Off Current	I_{CBO}	$V_{CB}=-50\text{V}$ $I_E=0$			-1.0	A
DC Current Gain	$h_{FE(1)^*}$	$V_{CE}=-4.0\text{V}$ $I_C=-1.0\text{A}^*$	60		320	
	$h_{FE(2)^*}$	$V_{CE}=-4.0\text{V}$ $I_C=-0.1\text{A}^*$	35			
Collector to Emitter Saturation Voltage*	$V_{CE(sat)^*}$	$I_C=-2.0\text{A}$ $I_B=-0.2\text{A}^*$			-1.0	V
Base to Emitter Voltage*	V_{BE}^*	$V_{CE}=-4.0\text{V}$ $I_C=-1.0\text{A}^*$			-1.0	V
Transition Frequency*	f_T^*	$V_{CE}=-4.0\text{V}$ $I_C=-0.5\text{A}^*$		15		MHz

* /Pulse test.

/ Electrical Characteristic Curve

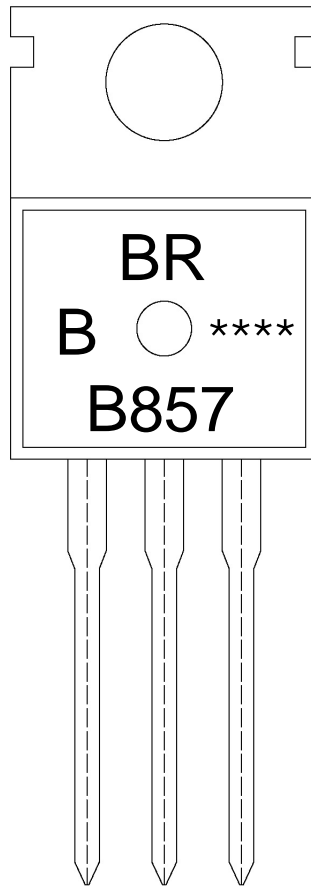


/ Package Dimensions



Symbol	Dimensions in millimeter		Symbol	Dimensions in millimeter	
	Min	Max		Min	Max
A	9.8	10.2	C	1.2	1.4
B	3.56	3.64	B1	6.3	6.7
B1	9.0	9.4	a	1.22	1.32
a	1.22	1.32	C	0.4	0.6
a1	1.25	1.45	b1	2.2	2.6
b1	2.2	2.6	C1	0.7	0.9
C	0.4	0.6	k	15.7	16.1
C1	0.7	0.9			
k	15.7	16.1			

/ Marking Instructions



BR

B857

B: h_{FE}

Note:

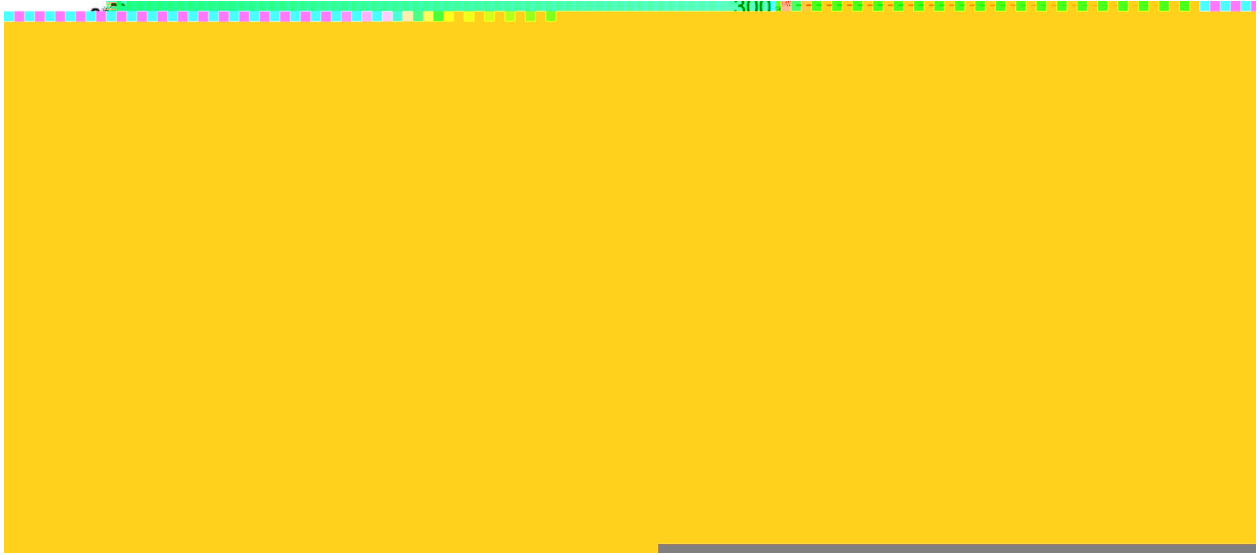
BR: Company Code

B857: Product Type.

B: h_{FE} Classifications Symbol

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



1	25	150	60	90sec;	Note:	1.Preheating:25~150 , Time:60~90sec.
2	255±5		5±0.5sec;		2.Peak Temp.:255±5 , Duration:5±0.5sec.	
3		2	10	/sec.	3. Cooling Speed: 2~10 /sec.	

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5℃ Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量		Dimension 包装尺寸 (unit: mm ³)	
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	In ②